

### **Description**

The WSF2060 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

### **General Features**

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation

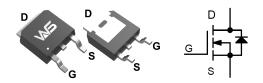
#### **Product Summery**

BVDSS	RDSON	ID		
20V	$3.5$ m $\Omega$	60A		

## **Application**

- Power switching application
- Hard switched
- Uninterruptible power supply

## **TO-252 Pin Configuration**



# Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter		Limit	Unit
VDS	Drain-Source Voltage		20	V
VGS	Gate-Source Voltage		±12	V
ID	Drain Current-Continuous		60	Α
ID*	Drain Current-Continuous	TC=100℃	52	Α
IDM	Pulsed Drain Current		320	Α
PD	Maximum Power Dissipation		83	W
	Derating factor		0.56	W/℃
EAS	Single pulse avalanche energy (Note 5)		280	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range		-55 To 175	${\mathbb C}$

### **Thermal Characteristic**

RθJC	Thermal Resistance,Junction-to-Case(Note 2)	1.8	°C/W
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# Electrical Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Тур	Max	Unit
Off Character	ristics					
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	20	-	-	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V	-	-	1	μA
Igss	Gate-Body Leakage Current	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
On Character	istics (Note 3)	•	•			
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	0.5	0.75	1.1	V
Rds(on)	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	3.5	5.5	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =20A	-	6	7.5	mΩ
<b>g</b> FS	Forward Transconductance	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	20	-	-	S
Dynamic Cha	racteristics (Note4)	•	_			
Clss	Input Capacitance	Vps=10V, Vgs=0V, F=1.0MHz	-	2016	-	PF
Coss	Output Capacitance		-	391	-	PF
Crss	Reverse Transfer Capacitance		-	130	-	PF
Switching Ch	aracteristics (Note 4)	•	-			
<b>t</b> d(on)	Turn-on Delay Time	V <sub>DD</sub> =10V, I <sub>D</sub> =20A V <sub>GS</sub> =10V, R <sub>GEN</sub> =2.7Ω	-	6	-	nS
tr	Turn-on Rise Time		-	4	-	nS
td(off)	Turn-Off Delay Time		-	31	-	nS
<b>t</b> f	Turn-Off Fall Time		-	5	-	nS
Qg	Total Gate Charge	V <sub>DS</sub> =10V I <sub>D</sub> =20A, V <sub>GS</sub> =4.5V	-	15	-	nC
Qgs	Gate-Source Charge		-	3	-	nC
$Q_{gd}$	Gate-Drain Charge		-	4	-	nC
Orain-Source	Diode Characteristics	•	_			
VsD	Diode Forward Voltage (Note 3)	V <sub>GS</sub> =0V,I <sub>S</sub> =20A	-	-	1.2	V
Is	Diode Forward Current (Note 2)		-	-	60	Α
trr	Reverse Recovery Time	TJ = 25°C, IF = 20A di/dt = 100A/μs(Note3)	-	18	-	nS
Qrr	Reverse Recovery Charge		-	30	-	nC

#### Notes:

- $\textbf{1.} \ \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}$ C,VDD=10V,VG=10V,L=0.5mH,Rg=25 $\Omega$



# Typical Electrical and Thermal Characteristics (Curves)

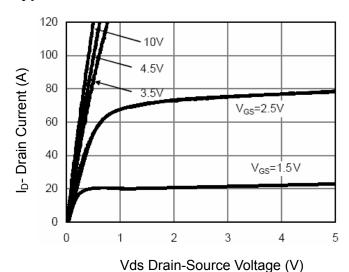


Figure 1 Output Characteristics

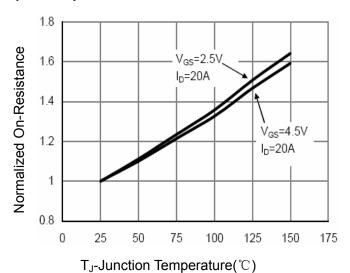
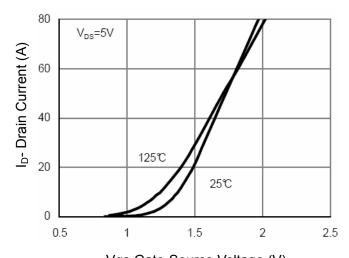


Figure 4 Rdson-Junction Temperature



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

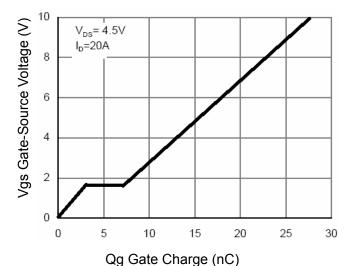


Figure 5 Gate Charge

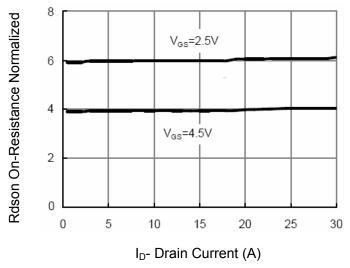


Figure 3 Rdson- Drain Current

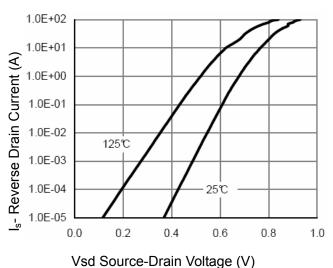


Figure 6 Source- Drain Diode Forward



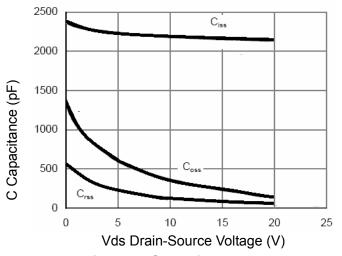
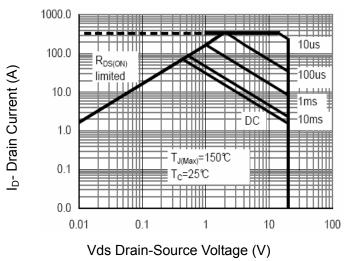


Figure 7 Capacitance vs Vds



**Figure 8 Safe Operation Area** 

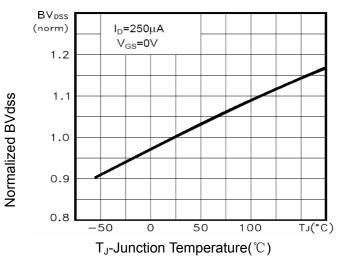
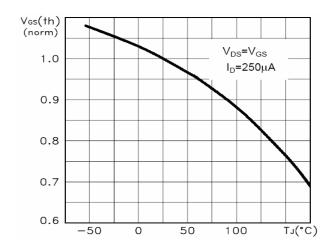
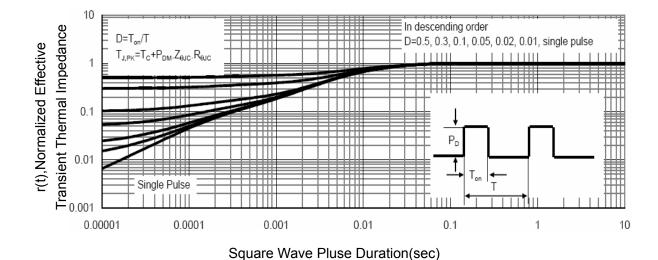


Figure 9 BV<sub>DSS</sub> vs Junction Temperature



 $T_J$ -Junction Temperature( $^{\circ}$ C)

Figure 10 V<sub>GS(th)</sub> vs Junction Temperature



**Figure 11 Normalized Maximum Transient Thermal Impedance** 



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